

SOT263-01

plastic single-ended package; heatsink mounted; 1 mounting hole; 5-lead TO-220 lead form option

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	TO-220-5 option
Package type industry code	TO-220-5 option
Package style descriptive code	ZFM (zig-zag flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	5-lead TO-220
Mounting method type	H (heatsink mount)
Issue date	14-2-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.2	-	15.5	15.8	mm
E	package width	9.7	-	10	10.3	mm
A	seated height	4.1	-	4.3	4.5	mm
n ₂	actual quantity of termination	-	-	5	-	



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2. Package outline

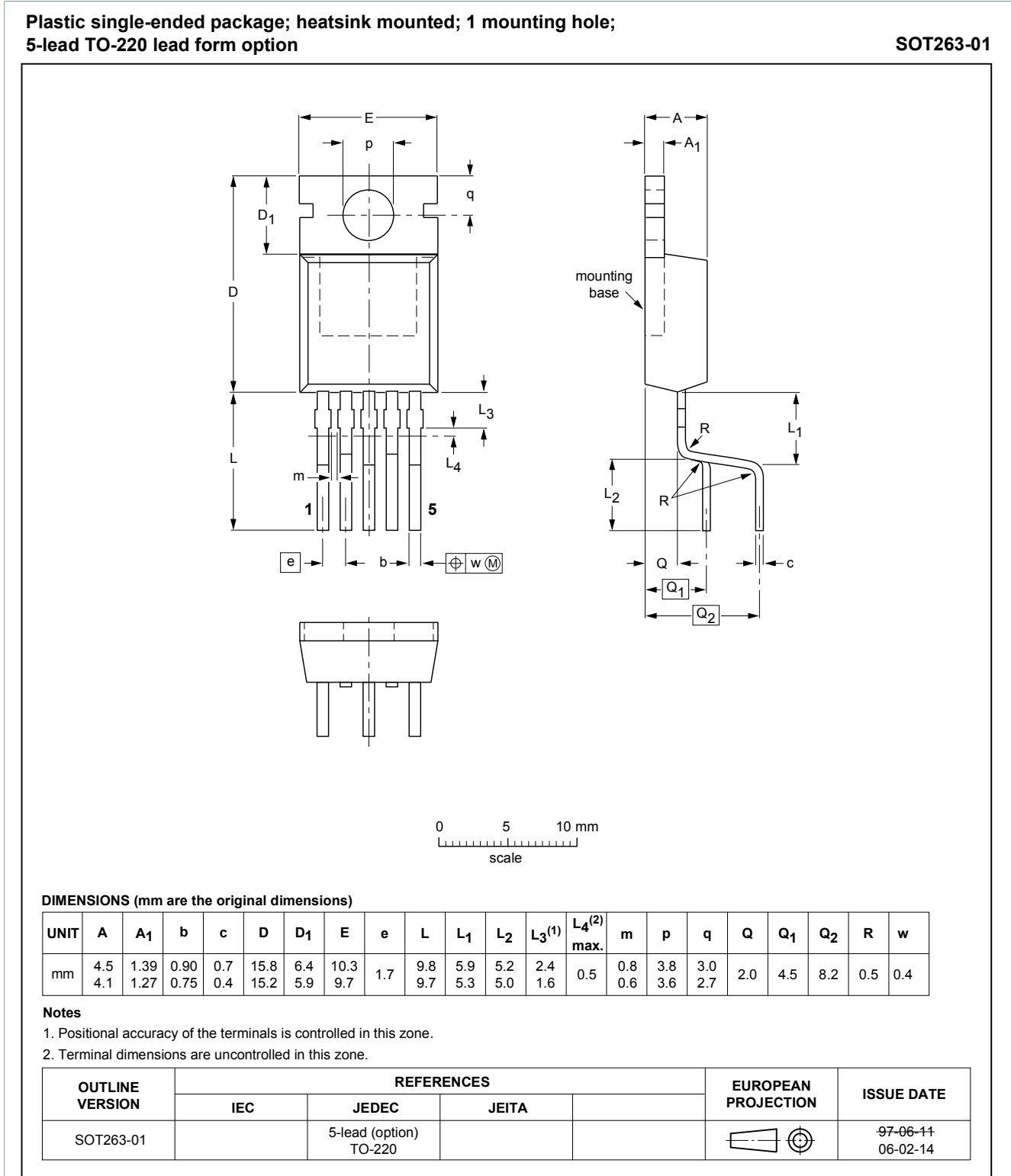


Fig. 1. Package outline TO-220-5 option (SOT263-01)

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3. Legal information

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